Revision: 1.0
Date: 7-Feb-05

Statement of Materials, Construction

8L OPLGA -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Substrate	BT Resin	0.01191	BT Epoxy	Proprietary	0.00517	27.82202	43.45
				Solder Mask	Proprietary	0.00183	9.82255	15.34
				Cu	7440-50-8	0.00469	25.22231	39.39
				Au	7440-57-5	0.00016	0.87724	1.37
				Ni	7440-02-0	0.00005	0.28815	0.45
2	Die	Silicon Chip	0.000770	Si	7440-21-3	0.00077	4.11909	99.5
3	Die attach material	Conductive Epoxy	0.000160	Epoxy resin	Proprietary	0.00002	0.12903	15
				Ag	7440-21-3	0.00013	0.68817	80
				Diester	Proprietary	0.00001	0.04301	5
				Functionalized Ester	Proprietary	0.00000	0.00000	0
4	Wire	Gold	0.0005600	Au	7440-57-5	0.00056	3.01045	99.99
5	Encapsulation	Epoxy Resin	0.0052	Bisphenol A type	25068-38-6	0.00281	15.09677	54
				Epoxy resin	2451-62-9	0.00083	4.47312	16
				Tetra Hydrophthalic Anhydride	85-43-8	0.001560	8.38710	30
				Halogenated Flame Retardants	Proprietary	0.00000	0.00000	0
Total Package weight			0.0186					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys